

MC68B44P Information

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General Information

Parameter	Value
Part Number	MC68B44P
Description	DMAC PLASTIC 2.0 MHZ
PTI	JBMM
Material Type	Tested Packaged Device
Life Cycle Description (code)	REMOVED FROM ACTIVE PORTFOLIO
Status	No Longer Manufactured

Package Information

Parameter	Value
Package Description and Mechanical Drawing	PDIP 40
Package Material	Plastic
Mounting Style	Through Hole
Package Length (nominal)(mm)	52.070
Package Width (nominal)(mm)	13.970
Package Thickness (nominal)(mm)	7.680
Tape & Reel	No

Environmental and Compliance Information

Parameter	Value
Pb-Free	Not Available
RoHS Compliant	Not Available
Material Composition Declaration (MCD)	Contact Us
RoHS Certificate of Analysis (CoA)	Contact Us
Peak Package Body Temperature (PPT)(°C)	Not Available
REACH SVHC	Freescale REACH Statement

Ordering Information

Parameter	Value
Last Order Date	07 May 1999
Last Ship Date	31 Dec 1999
Exempt from Minimum Delivery Value	Yes
Export Control Classification Number (US)	EAR99
Harmonized Tariff (US) Disclaimer	8542.31.0000
CCATS Document	-
ENC Status	-
Other Trade Compliance Documents	-
Budgetary Price excluding tax(US\$) Change Currency	-
Order	

Product/Process Change Notice (PCN)

Number	Type	Title	Issue Date	Effectivity Date
6480	Product Bulletin	UPDATE TO PB # 6191: ASSY TRANSFER, TIANJIN TO XIQING CHINA	14 Jun 2001	15 Jun 2001
6273	Product Change Notice	TEST MOVE FROM TJN TO XIQING CHINA	28 Feb 2001	01 Mar 2001
6191	Product Bulletin	ASSY TRANSFER, TIANJIN TO XIQING CHINA	30 Jan 2001	31 Jan 2001
4263	Product Discontinuance	PRODUCT DISCONTINUANCE OF VARIOUS MOS 3 EAST DEVICES	19 Feb 1999	19 Feb 1999
3934	Product Discontinuance	CANCELLATION OF THE 6844 DEVICE FAMILY	08 Sep 1998	08 Sep 1998
3218	Product Change Notice	INTRODUCTION OF NEW MOLD COMPOUND, HAREUS 1.0 MIL GOLD WIRE AND DIE ATTACH EPOXY FOR 40LD PDIP ASSEMBLY LINE IN TIANJIN	05 Mar 1998	15 Jun 1998
2674	Product Change Notice	CONVERSION TO 6" WAFERS IN MOS 3	29 May 1997	15 Sep 1997

Operating Characteristics

Parameter	Value
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